

ABSTRACT OF THE DISCLOSURE

A semiconductor package includes a package substrate and an integrated circuit. The package substrate has a first surface. The integrated circuit couples electrically to the first surface of the package substrate. The integrated circuit and the package substrate together form the semiconductor package. The semiconductor package also includes a first inductance circuit and a second inductance circuit, both formed within the semiconductor package. The first and second inductance circuits couple to each other in parallel. The first and second inductance circuits have substantially symmetrical geometric characteristics.

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